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(54) Title of Invention  
METHOD OF MANUFACTURING FLIP CHIP BUMP IN SEMICONDUCTOR PACKAGE

Representative drawing

(57) Abstract:

PURPOSE: A method of manufacturing a flip chip bump in a semiconductor package is provided to improve electrical contact between a probe tip and the surface of a bump in a chip test by removing organic materials on the metal bump with adding H<sub>2</sub> gas in a bump annealing process.

CONSTITUTION: A pad is formed on a semiconductor chip(10). A buffer layer is formed on the chip pad and the semiconductor chip. To expose the pad, the buffer layer is patterned to form an opening portion. An UBM layer(16a) is attached to the pad through the opening portion. A metal bump(22) is formed on the UBM layer. An annealing process is carried out with H<sub>2</sub> gas on the resultant structure.

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